

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t3518hfe#pbf

(Engineering Calculation)

TSSOP Exp. Pad

(printed on: 2020-07-11 19:06:09)

TOTAL MASS (g) : 0.054202

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|---------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002115 | 1000000 | 39020.8398438 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.014625 | 975000 | 269824.9375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000360 | 24000 | 6641.84472656 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 73.7982788086 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000010 | 700 | 184.495681763 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.014999 | 1000000 | 276725.09375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.002064 | 1000000 | 38076.328125 | | |
| | | External Plating Total: | | | | 0.002064 | 1000000 | 38076.328125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001037 | 1000000 | 19132.203125 | | |
| | | Internal Plating Total: | | | | 0.001037 | 1000000 | 19132.203125 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000712 | 750000 | 13136.09375 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000237 | 250000 | 4372.54785156 | | |
| Die Attach Total: | | | | 0.000949 | 1000000 | 17508.640625 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.004875 | 150000 | 89941.6484375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.026650 | 820000 | 491681 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000813 | 25000 | 14999.5 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000163 | 5000 | 3007.2800293 | | |
| | | Encapsulation Total: | | | | 0.032501 | 1000000 | 599629.4375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000537 | 1000000 | 9907.41894531 | | |
| | | | | | TOTAL MASS (g) : | 0.054202 | | |